



ABSTRACT OF THE DISCLOSURE

A multi-head type polishing apparatus has a plurality of top rings for holding workpieces with respect to a single polishing table. A polishing apparatus includes a
5 polishing table having a polishing surface, a plurality of top rings for holding workpieces and pressing the workpieces against the polishing surface, and a carousel for supporting the top rings and indexing the top rings. The polishing apparatus further includes a rotary transporter disposed in a
10 position which can be accessed by the top rings and having a plurality of portions positioned on a predetermined circumference from a center of rotation of the rotary transporter for holding the workpieces, and a pusher for transferring the workpieces between the rotary transporter and
15 the top rings.